

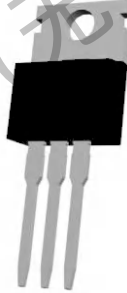
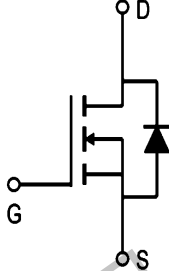


TMG160N15P

N-Channel Enhancement Mosfet

<p>General Description</p> <ul style="list-style-type: none"> • Low $R_{DS(ON)}$ • RoHS and Halogen-Free Compliant <p>Applications</p> <ul style="list-style-type: none"> • Load switch • PWM 	<p>General Features</p> <p>$V_{DS} = 150V$ $I_D = 160A$ $R_{DS(ON)} = 5.5m\Omega$(typ.) @ $V_{GS} = 10V$</p> <p>100% UIS Tested 100% R_g Tested</p> 
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P:TO-220AB

Marking: G160N15 G D S

Absolute Maximum Ratings: ($T_C = 25^\circ C$ unless otherwise noted)

Symbol	Parameter	Ratings	Units
V_{DS}	Drain-Source Voltage	150	V
V_{GS}	Gate-Source Voltage	± 20	V
I_D	Continuous Drain Current-	160	A
	Continuous Drain Current- $T_C = 100^\circ C$	112	
	Pulsed Drain Current	560	
E_{AS}	Single Pulse Avalanche Energy	625	mJ
P_D	Power Dissipation	192	W
T_J, T_{STG}	Operating and Storage Junction Temperature Range	-55 to +175	$^\circ C$

Thermal Characteristics:

Symbol	Parameter	Max	Units
$R_{\theta JC}$	Thermal Resistance, Junction to Case	1.67	$^\circ C/W$
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	62	

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Electrical Characteristics: ($T_C=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
Off Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\ \mu A$	150	---	---	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{GS}=0V, V_{DS}=150V$	---	---	1	μA
I_{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0A$	---	---	± 100	nA
On Characteristics						
$V_{GS(th)}$	GATE-Source Threshold Voltage	$V_{GS}=V_{DS}, I_D=250\ \mu A$	2	2.5	3	V
$R_{DS(ON)}$	Drain-Source On Resistance	$V_{GS}=10V, I_D=20A$	---	5.5	7	$m\ \Omega$
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{DS}=75V, V_{GS}=0V, f=1MHz$	---	5928	---	pF
C_{oss}	Output Capacitance		---	544	---	
C_{rss}	Reverse Transfer Capacitance		---	22	---	
Switching Characteristics						
$t_{d(on)}$	Turn-On Delay Time	$V_{DD}=75V, R_{GEN}=6\ \Omega, V_{GS}=10V$	---	31	---	ns
t_r	Rise Time		---	48	---	ns
$t_{d(off)}$	Turn-Off Delay Time		---	79	---	ns
t_f	Fall Time		---	45	---	ns
Q_g	Total Gate Charge		---	84.2	---	nC
Q_{gs}	Gate-Source Charge	$V_{GS}=10V, V_{DS}=75V,$	---	23.8	---	nC
Q_{gd}	Gate-Drain "Miller" Charge	$I_D=20A$	---	16.8	---	nC
Drain-Source Diode Characteristics						
V_{SD}	Source-Drain Diode Forward Voltage	$V_{GS}=0V, I_S=1A$	---	0.6	1	V
I_S	Diode Forward Current ¹	$V_D=V_G=0V$	---	---	160	A
I_{SM}	Diode Forward Current	$V_D=V_G=0V$	---	---	440	A
T_{rr}	Reverse Recovery Time	$T_j=25^\circ\text{C}, I_F=15A$ $di/dt=100A/\mu s$	---	92	---	NS
Q_{rr}	Reverse Recovery Charge		---	364	---	NC



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Typical Characteristics

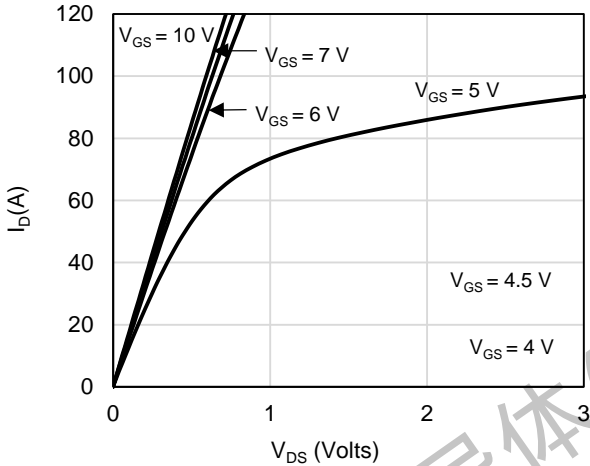


Figure 1: On-Region Characteristics

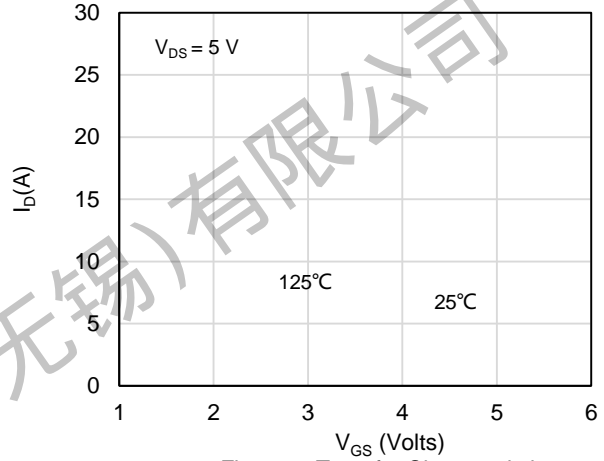


Figure 2: Transfer Characteristics

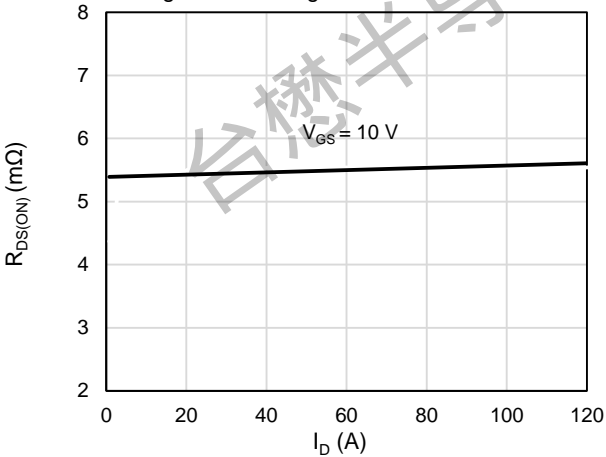


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

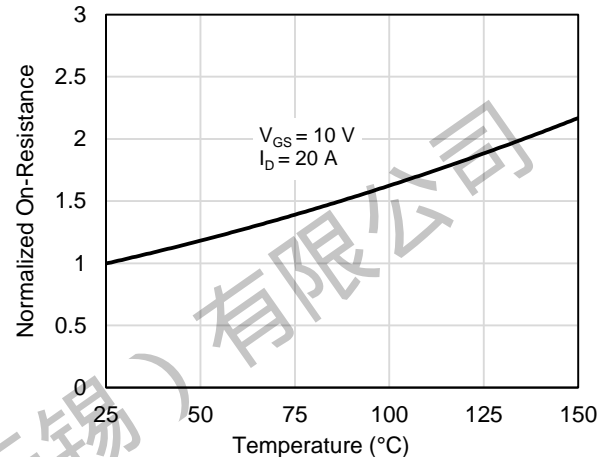


Figure 4: On-Resistance vs. Junction Temperature

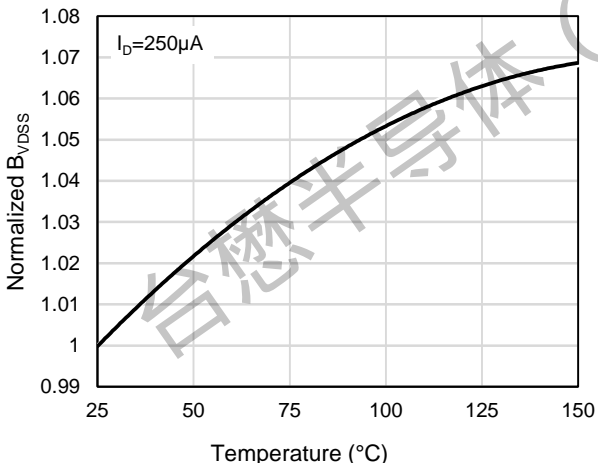


Figure 5: Breakdown Voltage vs. Junction Temperature

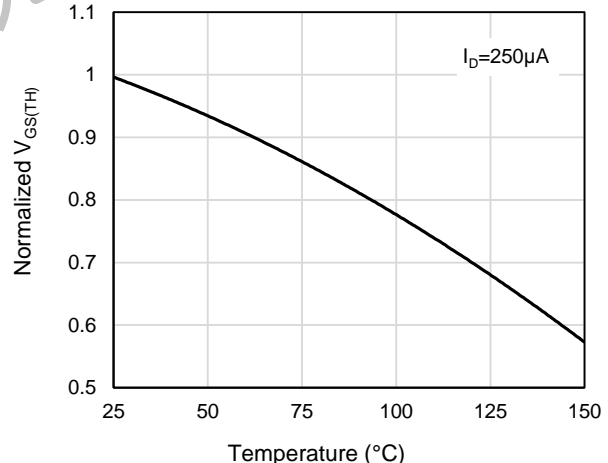


Figure 6: Threshold Voltage vs. Junction Temperature



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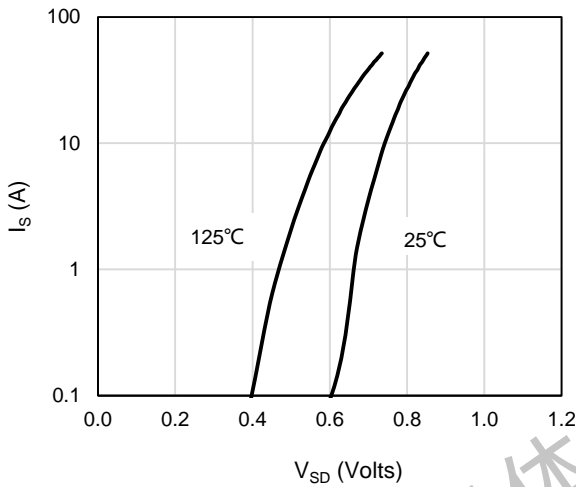


Figure 7: Body-Diode Characteristics

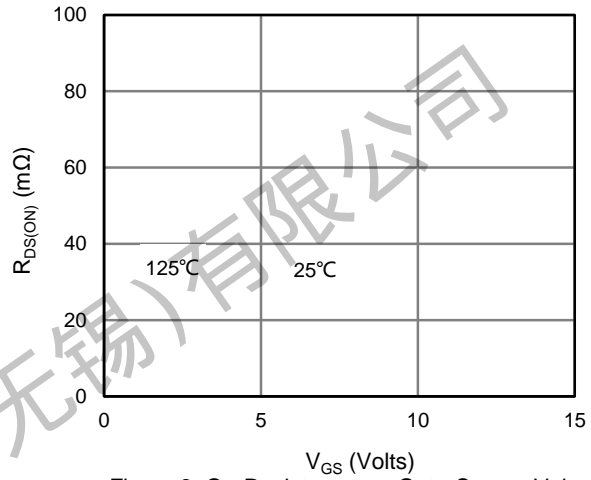


Figure 8: On-Resistance vs. Gate-Source Voltage

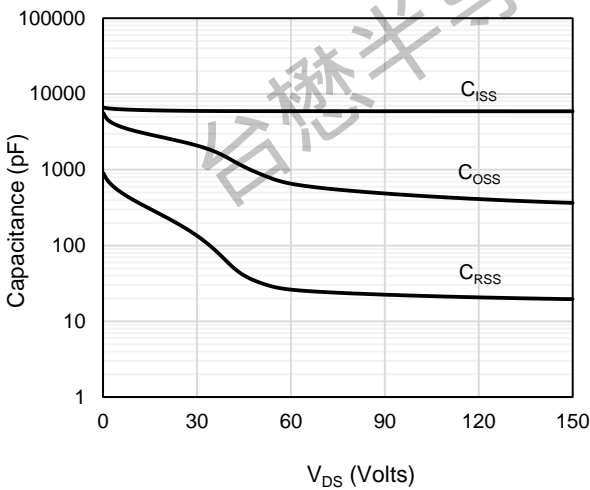


Figure 9: Capacitance Characteristics

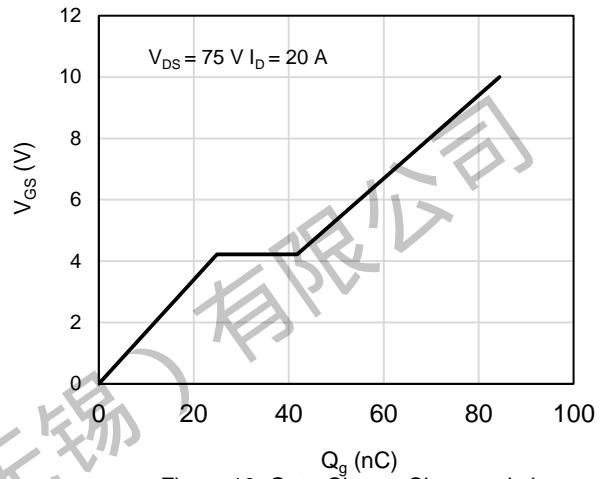


Figure 10: Gate-Charge Characteristics

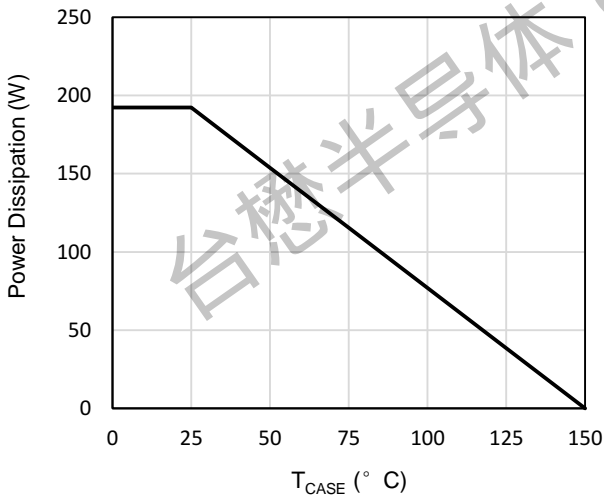


Figure 11: Power De-rating

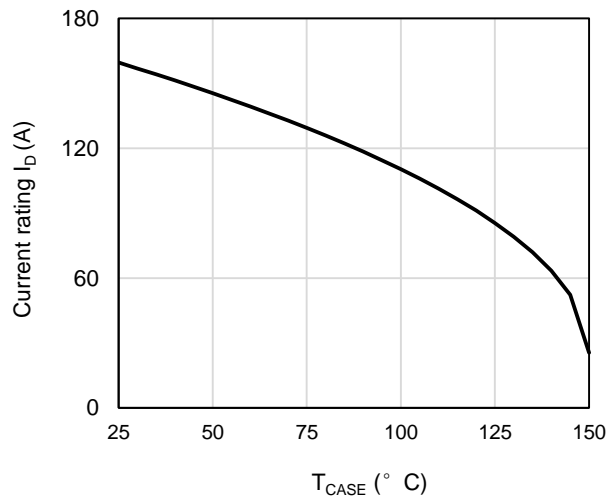


Figure 12: Current De-rating



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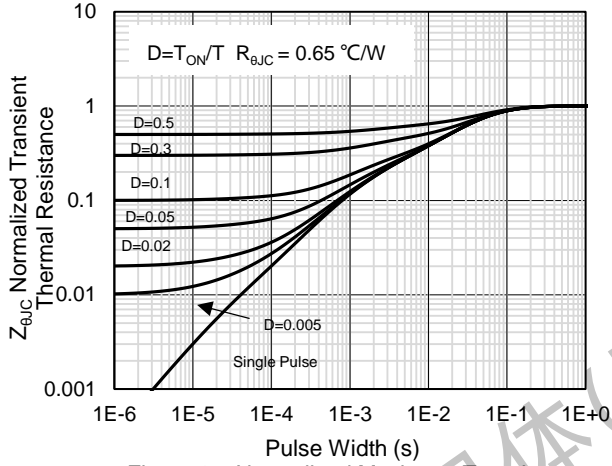


Figure 13: Normalized Maximum Transient Thermal Impedance

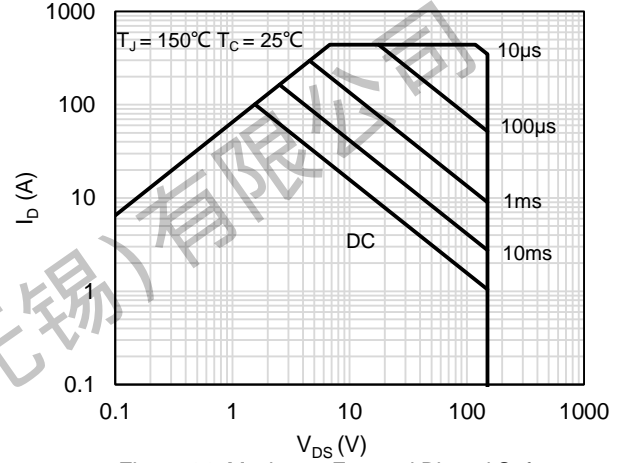
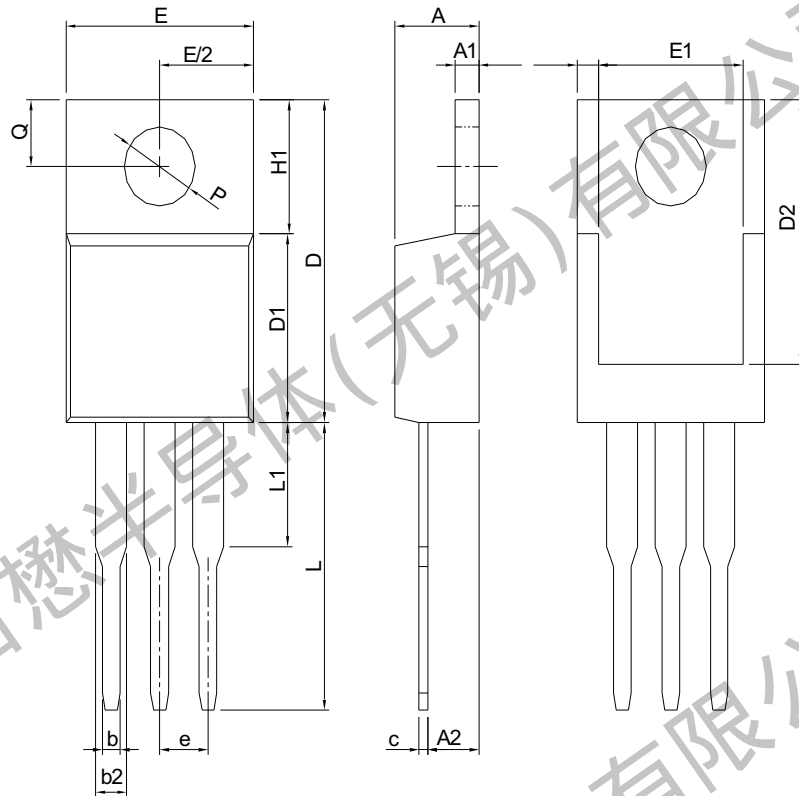


Figure 14: Maximum Forward Biased Safe Operating Area

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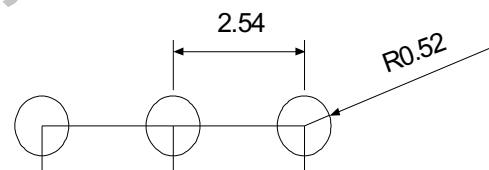
N-Channel Enhancement Mosfet

Package Mechanical Data: TO-220AB



DIMENSIONS	TO-220			
	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	3.56	4.83	0.140	0.190
A1	0.51	1.40	0.020	0.055
A2	2.03	2.92	0.080	0.115
b	0.38	1.02	0.015	0.040
b2	1.14	1.78	0.045	0.070
c	0.36	0.61	0.014	0.024
D	14.22	16.51	0.560	0.650
D1	8.38	9.02	0.330	0.355
D2	12.19	13.65	0.480	0.537
E	9.65	10.67	0.380	0.420
E1	6.86	8.89	0.270	0.350
e	2.54 BSC		0.100 BSC	
H1	5.84	6.86	0.230	0.270
L	12.70	14.73	0.500	0.580
L1	-	6.35	-	0.250
P	3.53	4.09	0.139	0.161
Q	2.54	3.43	0.100	0.135

RECOMMENDED LAND PATTERN

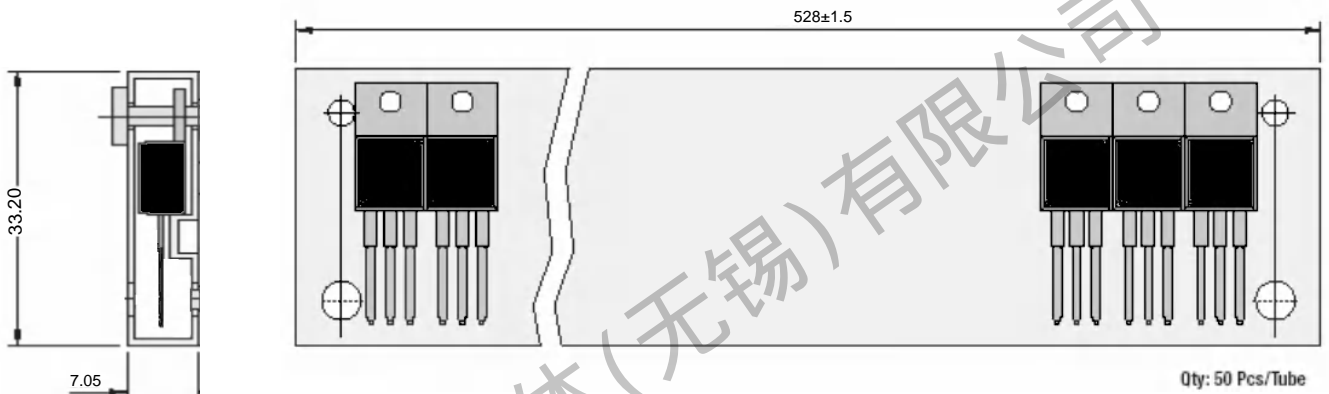


UNIT: mm

Note: Follow JEDEC TO-220 AB.

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All Dimensions are in mm

1.TO-220AB Packaging

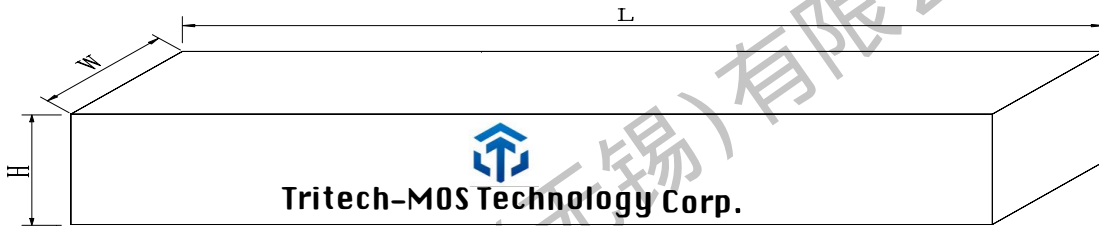
Package	Packing Form	Quantity		
		Tube	Inner Box [kpcs]	Outbox [kpcs]
TO-220AB	Tube Tape	50	5	1



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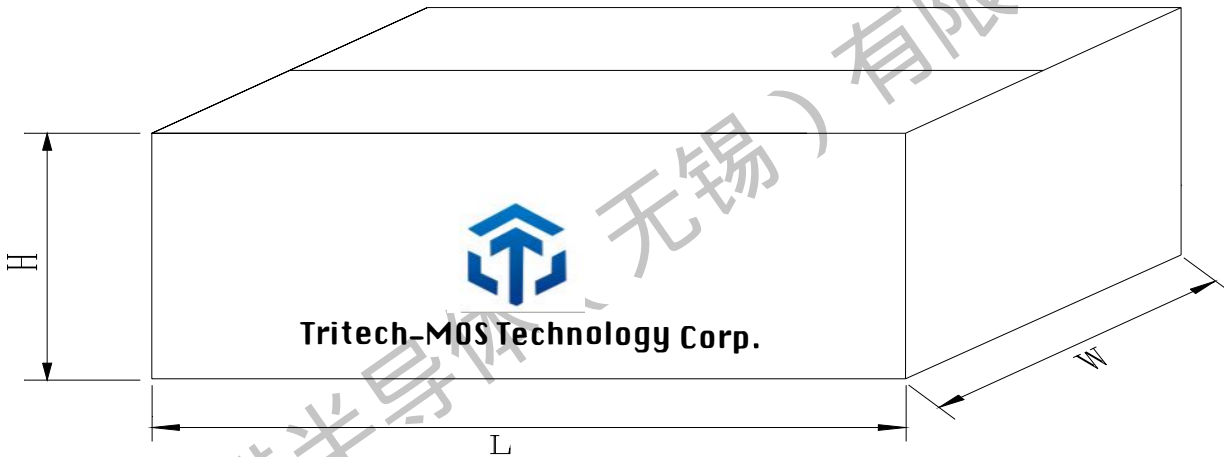
Inner Box



Dimension : 580 (L)×154(W) ×49(H) mm

Quantity : 50 ×20Ea = 1Kpcs

Outer Box



Dimension : 595(L)×285(W) ×185(H) mm

Quantity : 1K×5Ea = 5Kpcs

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Revision history:

Date	Rev	Description	Page
2023.08.11	23.08	Original	